What is claimed is:

1. A polishing apparatus, comprising:

a polishing table configured to support a polishing pad;

a top ring configured to press a substrate against the polishing pad; and

a liquid supply mechanism configured to supply a liquid onto the polishing pad,

wherein the liquid supply mechanism comprises:

a nozzle arm configured to be movable in a radial direction of the polishing table;

a liquid ejection nozzle attached to the nozzle arm, the liquid ejection nozzle being a fan-shaped nozzle having a liquid throttle surface, the liquid throttle surface being formed on an inner surface of the liquid ejection nozzle and having a tapered shape;

a slurry nozzle attached to the nozzle arm, the slurry nozzle being disposed above a center of the polishing pad when the nozzle arm is in a processing position, the liquid ejection nozzle being disposed at a region between the center of the polishing pad and an outer peripheral portion of the polishing pad when the nozzle arm is in the processing position;

a nozzle cleaning device disposed outside the polishing pad,

wherein the nozzle cleaning device comprises:

a first cleaning nozzle configured to clean the slurry nozzle; and

a second cleaning nozzle configured to clean the liquid ejection nozzle.

2. The polishing apparatus according to claim 1, wherein the liquid supply mechanism comprises:

a slurry line coupled to the liquid ejection nozzle and flowing a

polishing liquid;

a flushing line coupled to the liquid ejection nozzle and flowing a flushing liquid for cleaning the liquid ejection nozzle.

3. The polishing apparatus according to claim 1, further comprising an atomizer configured to eject a cleaning fluid onto the polishing pad,

wherein the liquid supply mechanism comprises a dressing liquid supply device attached to the atomizer.

4. The polishing apparatus according to claim 1, wherein:

the liquid supply mechanism comprises a slurry nozzle attached to the nozzle arm; and

the slurry nozzle and the liquid ejection nozzle are disposed above a center of the polishing pad when the nozzle arm is in a processing position.